PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DUSTIN WILLIAM ERICKSON	09/09/2015
XUETI TANG	09/04/2015
JANGEUN LEE	09/11/2015
EUGENE CHEN	09/04/2015

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRONICS CO., LTD.	
Street Address:	129 SAMSUNG-RO, YEONGTONG-GU	
Internal Address:	SUWON-SI	
City:	GYEONGGI-DO	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	443-742	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14852422

CORRESPONDENCE DATA

Fax Number: (650)318-3374

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 650-318-3374

Email: patents@convergentlaw.com

Correspondent Name: CONVERGENT LAW GROUP LLP

Address Line 1: 475 N. WHISMAN ROAD, SUITE 400

Address Line 4: MOUNTAIN VIEW, CALIFORNIA 94043

ATTORNEY DOCKET NUMBER:	NMT010US	
NAME OF SUBMITTER:	DEBBIE NISHIHARA	
SIGNATURE:	/DebbieNishihara/	
DATE SIGNED:	IGNED: 09/11/2015	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 2

PATENT REEL: 036547 FRAME: 0941

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PATENT REEL: 036547 FRAME: 0942

Docket No: NMT010US

DECLARATION AND ASSIGNMENT FOR PATENT APPLICATION

Title of Invention: METHOD FOR PROVIDING FOR THIN (001) ORIENTATION MgO LAYERS FOR MAGNETIC JUNCTIONS USABLE IN SPIN TRANSFER TORQUE MAGNETIC MEMORY APPLICATIONS AND THE MAGNETIC JUNCTIONS SO FORMED

As a below named inventor, I hereby declare that:				
This declaration is directed to the attached application, or (if following box is checked):				
[] US Application or PCT Application No.	filed on			
The above-identified application was made or authorized to be made by me.				

I believe I am the original inventor (if only one name is listed below) or an original joint inventor (if plural names are listed below) of the subject matter which is claimed.

I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

For good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned inventor(s), do hereby sell, assign, and transfer to: Samsung Electronics Co., LTD., a corporation having a principal place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea 443-742 ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the above-identified application and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Each of the undersigned inventors agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

And the Assignors hereby authorize and request the attorneys and agents to insert in the spaces provided above the title of the invention, filing date, application number, and attorney's docket number of said application when known.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and acknowledge that willful false statements and the like so made are punishable under Section 1001 of Title 18 of the United States Code by fine or imprisonment of not more than five (5) years, or both.

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DECLARATION FOR PATENT APPLICATION (continued)

Full Name of Inventor: <u>Dustin William Erickson</u>	***************************************
Signature	9/9/15 Date
Full Name of Inventor: Xueti Tang	***************************************
XIII	9/4/2015
Signature	Date
Full Name of Inventor: Jangeun Lee	E0000000000000000000000000000000000000
9 28 E	9/11/20/5
Inventor's Signature	Date
Full Name of Inventor: Eugene Chen	***************************************
hylescha	9/4/15
Inventor's Signature	Date